

## High Efficiency Thyristor

$$V_{RRM} = 1200V$$

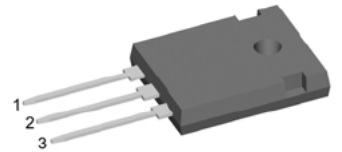
$$I_{TAV} = 50A$$

$$V_T = 1.27V$$

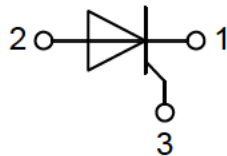
### Single Thyristor

#### Part number

CLA50E1200HB



Backside: anode



#### Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

#### Applications:

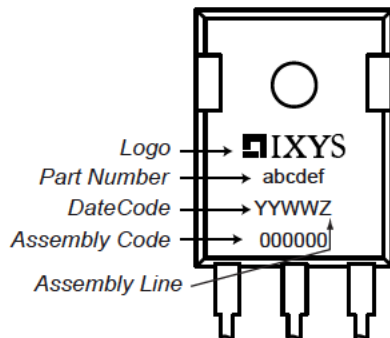
- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

#### Package: TO-247

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Thyristor				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$			1300	V	
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$			1200	V	
$I_{RD}$	reverse current, drain current	$V_{RD} = 1200\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$		50	$\mu\text{A}$	
		$V_{RD} = 1200\text{ V}$	$T_{VJ} = 125^{\circ}\text{C}$		4	mA	
$V_T$	forward voltage drop	$I_T = 50\text{ A}$	$T_{VJ} = 25^{\circ}\text{C}$		1.32	V	
					1.60	V	
		$I_T = 100\text{ A}$	$T_{VJ} = 125^{\circ}\text{C}$		1.27	V	
					1.65	V	
$I_{TAV}$	average forward current	$T_C = 125^{\circ}\text{C}$	$T_{VJ} = 150^{\circ}\text{C}$		50	A	
$I_{T(RMS)}$	RMS forward current	180° sine			79	A	
$V_{TD}$	threshold voltage	} for power loss calculation only	$T_{VJ} = 150^{\circ}\text{C}$		0.88	V	
$r_T$	slope resistance				7.7	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case				0.25	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W	
$P_{tot}$	total power dissipation		$T_C = 25^{\circ}\text{C}$		500	W	
$I_{TSM}$	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}\text{C}$		650	A	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		700	A	
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}\text{C}$		555	A	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		595	A	
$I^2t$	value for fusing	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}\text{C}$		2.12	kA <sup>2</sup> s	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		2.04	kA <sup>2</sup> s	
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}\text{C}$		1.54	kA <sup>2</sup> s	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		1.48	kA <sup>2</sup> s	
$C_J$	junction capacitance	$V_R = 400\text{ V}$ $f = 1\text{ MHz}$	$T_{VJ} = 25^{\circ}\text{C}$		25	pF	
$P_{GM}$	max. gate power dissipation	$t_p = 30\text{ }\mu\text{s}$	$T_C = 150^{\circ}\text{C}$		10	W	
		$t_p = 300\text{ }\mu\text{s}$			5	W	
$P_{GAV}$	average gate power dissipation				0.5	W	
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 150^{\circ}\text{C}; f = 50\text{ Hz}$ repetitive, $I_T = 150\text{ A}$			150	A/ $\mu\text{s}$	
		$t_p = 200\text{ }\mu\text{s}; di_G/dt = 0.3\text{ A}/\mu\text{s}; I_G = 0.3\text{ A}; V_D = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 50\text{ A}$			500	A/ $\mu\text{s}$	
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$ ; method 1 (linear voltage rise)	$T_{VJ} = 150^{\circ}\text{C}$		1000	V/ $\mu\text{s}$	
$V_{GT}$	gate trigger voltage	$V_D = 6\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$		1.5	V	
			$T_{VJ} = -40^{\circ}\text{C}$		1.6	V	
$I_{GT}$	gate trigger current	$V_D = 6\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$		50	mA	
			$T_{VJ} = -40^{\circ}\text{C}$		80	mA	
$V_{GD}$	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^{\circ}\text{C}$		0.2	V	
$I_{GD}$	gate non-trigger current				3	mA	
$I_L$	latching current	$t_p = 10\text{ }\mu\text{s}$	$T_{VJ} = 25^{\circ}\text{C}$		125	mA	
		$I_G = 0.3\text{ A}; di_G/dt = 0.3\text{ A}/\mu\text{s}$					
$I_H$	holding current	$V_D = 6\text{ V}$ $R_{GK} = \infty$	$T_{VJ} = 25^{\circ}\text{C}$		100	mA	
$t_{gd}$	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^{\circ}\text{C}$		2	$\mu\text{s}$	
		$I_G = 0.3\text{ A}; di_G/dt = 0.3\text{ A}/\mu\text{s}$					
$t_q$	turn-off time	$V_R = 100\text{ V}; I_T = 50\text{ A}; V_D = \frac{2}{3} V_{DRM}$ $di/dt = 10\text{ A}/\mu\text{s}; dv/dt = 20\text{ V}/\mu\text{s}; t_p = 200\text{ }\mu\text{s}$	$T_{VJ} = 150^{\circ}\text{C}$		200	$\mu\text{s}$	

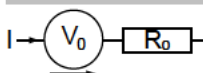
Package TO-247			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			70	A
$T_{stg}$	storage temperature		-55		150	°C
$T_{vj}$	virtual junction temperature		-40		150	°C
<b>Weight</b>				6		g
$M_D$	mounting torque		0.8		1.2	Nm
$F_c$	mounting force with clip		20		120	N

**Product Marking**

**Part number**

C = Thyristor (SCR)  
 L = High Efficiency Thyristor  
 A = (up to 1200V)  
 50 = Current Rating [A]  
 E = Single Thyristor  
 1200 = Reverse Voltage [V]  
 HB = TO-247AD (3)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CLA50E1200HB	CLA50E1200HB	Tube	30	503748

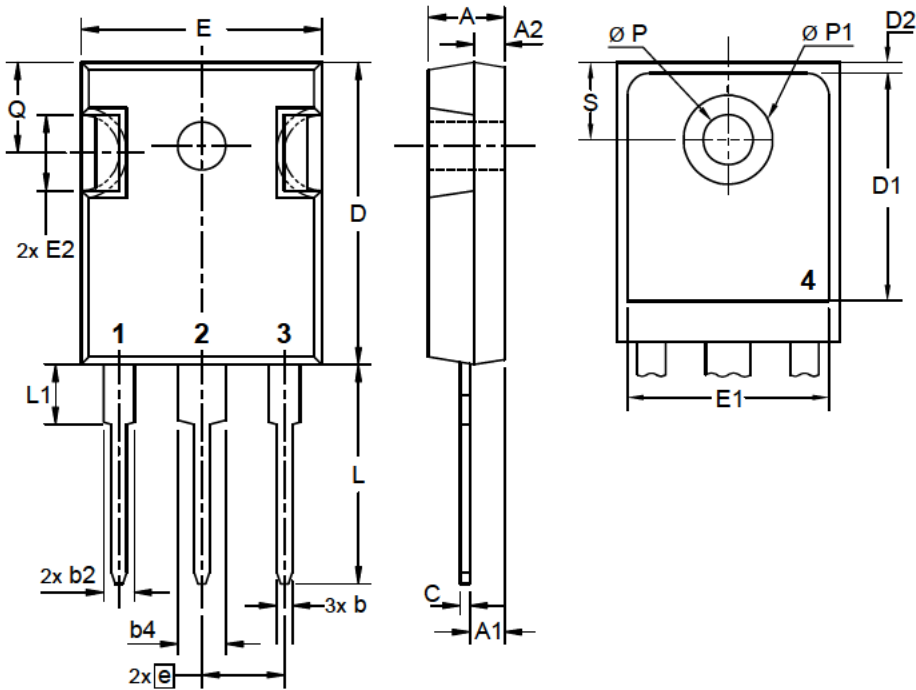
Similar Part	Package	Voltage class
CLA50E1200TC	TO-268AA (D3Pak) (2)	1200

**Equivalent Circuits for Simulation**
*\* on die level*
 $T_{vj} = 150^{\circ}\text{C}$ 


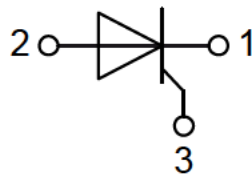
Thyristor

$V_{0\max}$	threshold voltage	0.88	V
$R_{0\max}$	slope resistance *	5.2	mΩ

**Outlines TO-247**



Sym.	Inches		Millimeter	
	min.	max.	min.	max.
A	0.185	0.209	4.70	5.30
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.50	2.49
D	0.819	0.845	20.79	21.45
E	0.610	0.640	15.48	16.24
E2	0.170	0.216	4.31	5.48
e	0.215	BSC	5.46	BSC
L	0.780	0.800	19.80	20.30
L1	-	0.177	-	4.49
Ø P	0.140	0.144	3.55	3.65
Q	0.212	0.244	5.38	6.19
S	-	0.242 BSC	-	6.14 BSC
b	0.039	0.055	0.99	1.40
b2	0.065	0.094	1.65	2.39
b4	0.102	0.135	2.59	3.43
c	0.015	0.035	0.38	0.89
D1	0.515	-	13.07	-
D2	0.020	0.053	0.51	1.35
E1	0.530	-	13.45	-
Ø P1	-	0.29	-	7.39



**Thyristor**

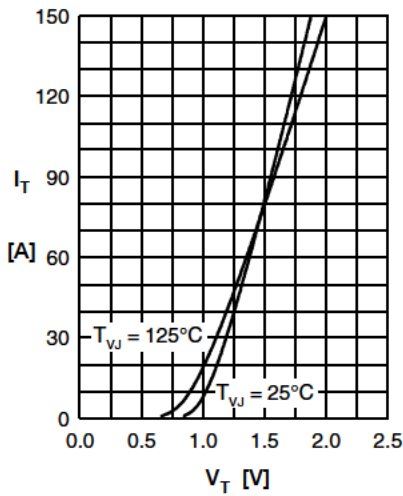


Fig. 1 Forward characteristics

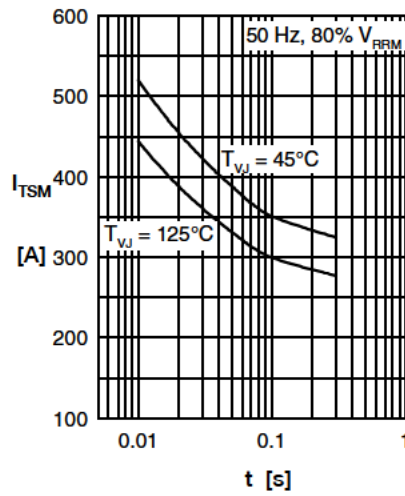


Fig. 2 Surge overload current  
 $I_{TSM}$ : crest value, t: duration

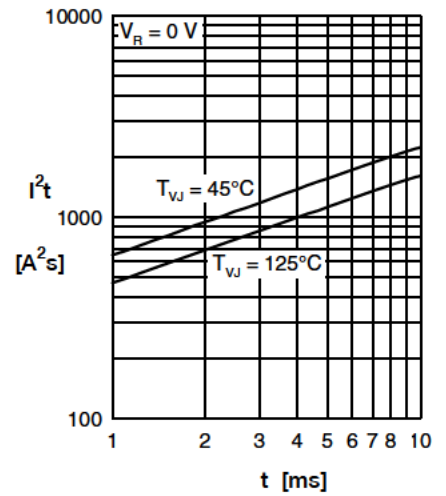


Fig. 3  $I^2t$  versus time (1-10 s)

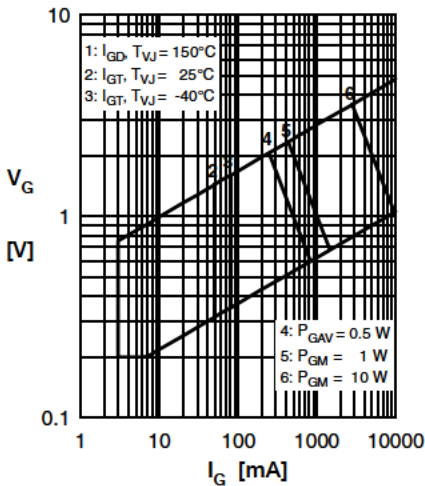


Fig. 4 Gate voltage & gate current

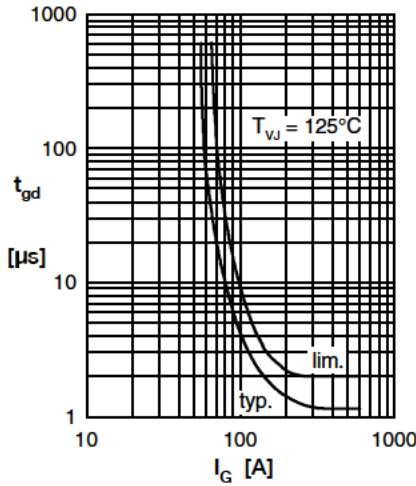


Fig. 5 Gate controlled delay time  $t_{gd}$

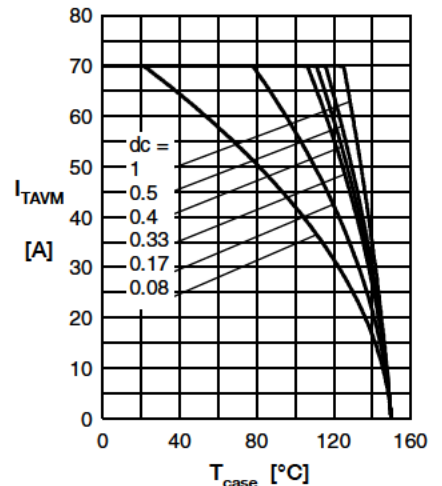


Fig. 6 Max. forward current at case temperature

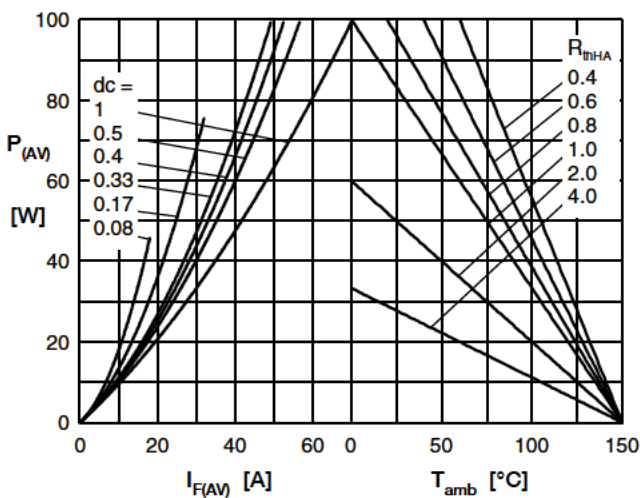


Fig. 7a Power dissipation versus direct output current  
Fig. 7b and ambient temperature

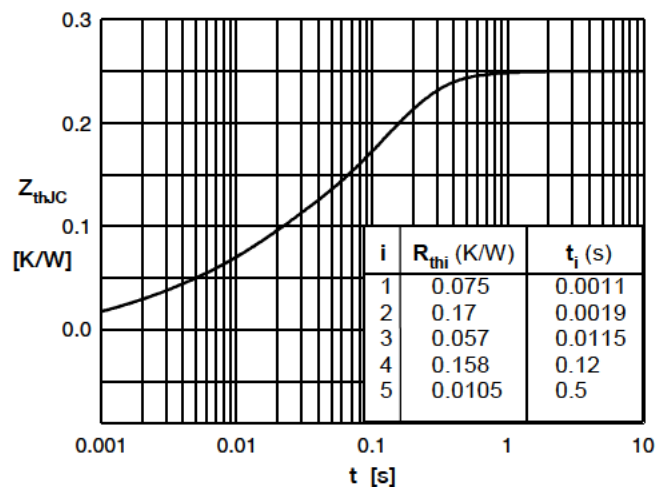


Fig. 7 Transient thermal impedance junction to case